



Data sheet acquired from Harris Semiconductor
SCHS115D – Revised September 2003

CMOS Quad 2-Input NAND Schmitt Triggers

High-Voltage Types (20 Volt Rating)

■ CD4093B consists of four Schmitt-trigger circuits. Each circuit functions as a two-input NAND gate with Schmitt-trigger action on both inputs. The gate switches at different points for positive- and negative-going signals. The difference between the positive voltage (V_P) and the negative voltage (V_N) is defined as hysteresis voltage (V_H) (see Fig. 2).

The CD4093B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})	 -0.5V to +20V
Voltages referenced to V_{SS} Terminal)	 -0.5V to $V_{DD} + 0.5V$
INPUT VOLTAGE RANGE, ALL INPUTS	 -0.5V to $V_{DD} + 0.5V$
DC INPUT CURRENT, ANY ONE INPUT	 $\pm 10\text{mA}$
PACKAGE THERMAL IMPEDANCE, θ_{JA} (See Note 1):	
E package	 80°C/W
M package	 86°C/W
NS package	 76°C/W
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	 100mW
OPERATING-TEMPERATURE RANGE (T_A)	 -55°C to $+125^\circ\text{C}$
STORAGE TEMPERATURE RANGE (T_{stg})	 -65°C to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ inch ($1.59 \pm 0.79\text{mm}$) from case for 10s max	 $+265^\circ\text{C}$

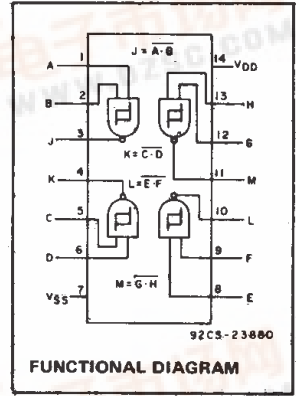
NOTE 1: Package thermal impedance is calculated in accordance with JESD 51-7.

Features:

- Schmitt-trigger action on each input with no external components
- Hysteresis voltage typically 0.9 V at $V_{DD} = 5\text{ V}$ and 2.3 V at $V_{DD} = 10\text{ V}$
- Noise immunity greater than 50%
- No limit on input rise and fall times
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of $1\text{ }\mu\text{A}$ at 18 V over full package-temperature range, 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Wave and pulse shapers
- High-noise-environment systems
- Monostable multivibrators
- Astable multivibrators
- NAND logic



RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	MIN.	MAX.	UNITS
Supply Voltage Range (T_A = Full Package Temp. Range)	3	18	V



* ALL INPUTS PROTECTED BY CMOS PROTECTION NETWORK

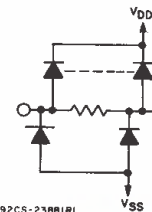


Fig. 1 – Logic diagram – 1 of 4 Schmitt triggers.

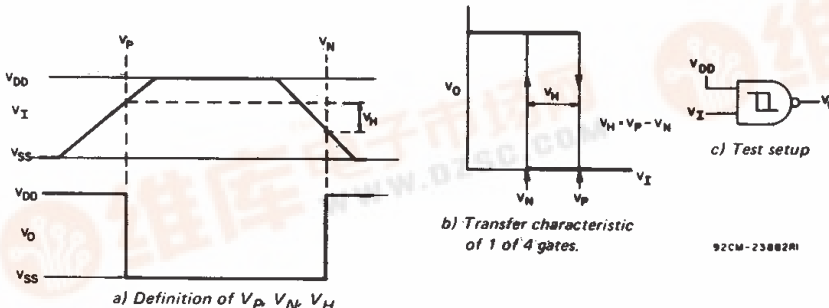


Fig. 2 – Hysteresis definition, characteristic, and test setup.

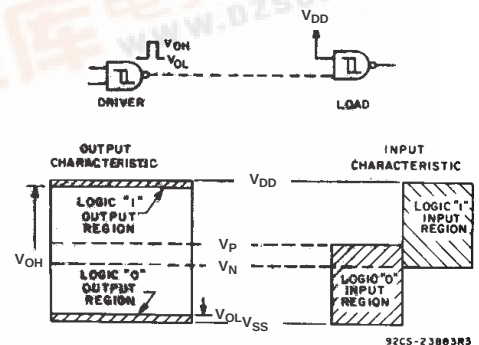


Fig. 3 – Input and output characteristics.



CD4093B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								MIN.	TYP.	MAX.	
Quiescent Device Current, I _{DD} Max.	—	0.5	5	1	1	30	30	—	0.02	1	μA
	—	0.10	10	2	2	60	60	—	0.02	2	
	—	0.15	15	4	4	120	120	—	0.02	4	
	—	0.20	20	20	20	600	600	—	0.04	20	
Positive Trigger Threshold Voltage V _p Min.	—	a	5	2.2	2.2	2.2	2.2	2.2	2.9	—	V
	—	a	10	4.6	4.6	4.6	4.6	4.6	5.9	—	
	—	a	15	6.8	6.8	6.8	6.8	6.8	8.8	—	
	—	b	5	2.6	2.6	2.6	2.6	2.6	3.3	—	
	—	b	10	5.6	5.6	5.6	5.6	5.6	7	—	
	—	b	15	6.3	6.3	6.3	6.3	6.3	9.4	—	
V _p Max.	—	a	5	3.6	3.6	3.6	3.6	—	2.9	3.6	V
	—	a	10	7.1	7.1	7.1	7.1	—	5.9	7.1	
	—	a	15	10.8	10.8	10.8	10.8	—	8.8	10.8	
	—	b	5	4	4	4	4	—	3.3	4	
	—	b	10	8.2	8.2	8.2	8.2	—	7	8.2	
	—	b	15	12.7	12.7	12.7	12.7	—	9.4	12.7	
Negative Trigger Threshold Voltage V _N Min.	—	a	5	0.9	0.9	0.9	0.9	0.9	1.9	—	V
	—	a	10	2.5	2.5	2.5	2.5	2.5	3.9	—	
	—	a	15	4	4	4	4	4	5.8	—	
	—	b	5	1.4	1.4	1.4	1.4	1.4	2.3	—	
	—	b	10	3.4	3.4	3.4	3.4	3.4	5.1	—	
	—	b	15	4.8	4.8	4.8	4.8	4.8	7.3	—	
V _N Max.	—	a	5	2.8	2.8	2.8	2.8	—	1.9	2.8	V
	—	a	10	5.2	5.2	5.2	5.2	—	3.9	5.2	
	—	a	15	7.4	7.4	7.4	7.4	—	5.8	7.4	
	—	b	5	3.2	3.2	3.2	3.2	—	2.3	3.2	
	—	b	10	6.6	6.6	6.6	6.6	—	5.1	6.6	
	—	b	15	9.6	9.6	9.6	9.6	—	7.3	9.6	
Hysteresis Voltage V _H Min.	—	a	5	0.3	0.3	0.3	0.3	0.3	0.9	—	V
	—	a	10	1.2	1.2	1.2	1.2	1.2	2.3	—	
	—	a	15	1.6	1.6	1.6	1.6	1.6	3.5	—	
	—	b	5	0.3	0.3	0.3	0.3	0.3	0.9	—	
	—	b	10	1.2	1.2	1.2	1.2	1.2	2.3	—	
	—	b	15	1.6	1.6	1.6	1.6	1.6	3.5	—	
V _H Max.	—	a	5	1.6	1.6	1.6	1.6	—	0.9	1.6	V
	—	a	10	3.4	3.4	3.4	3.4	—	2.3	3.4	
	—	a	15	5	5	5	5	—	3.5	5	
	—	b	5	1.6	1.6	1.6	1.6	—	0.9	1.6	
	—	b	10	3.4	3.4	3.4	3.4	—	2.3	3.4	
	—	b	15	5	5	5	5	—	3.5	5	

^a Input on terminals 1, 5, 8, 12 or 2, 6, 9, 13; other inputs to V_{DD} .

^b Input on terminals 1 and 2, 5 and 6, 8 and 9, or 12 and 13; other inputs to V_{DD} .

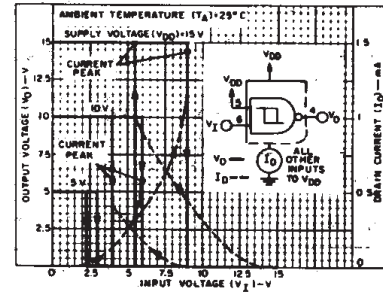


Fig. 4 — Typical current and voltage transfer characteristics.

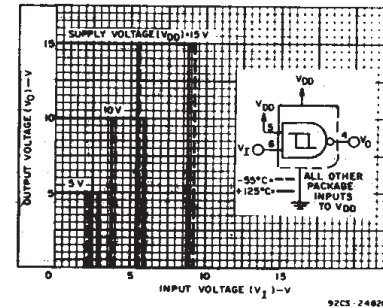


Fig. 5 — Typical voltage transfer characteristics as a function of temperature.

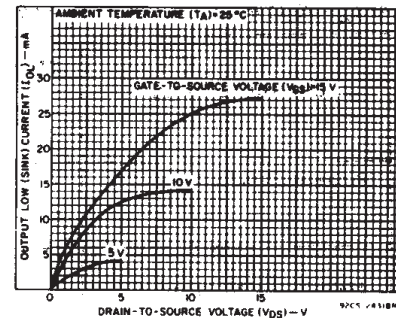


Fig. 6 — Typical output low (sink) current characteristics.

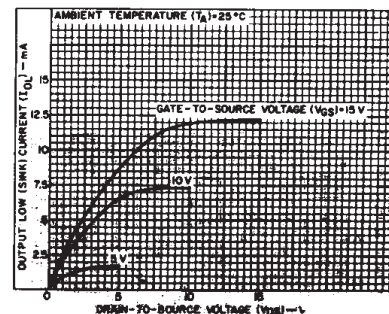


Fig. 7 — Minimum output low (sink) current characteristics.

CD4093B Types

STATIC ELECTRICAL CHARACTERISTICS (CONT'D)

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								MIN.	TYP.	MAX.	
Output Low (Sink) Current, I _{OL} Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage Low-Level, V _{OL} Max.	—	0.5	5	0.05			—	0	0.05	V	
	—	0.10	10	0.05			—	0	0.05		
	—	0.15	15	0.05			—	0	0.05		
Output Voltage High-Level, V _{OH} Min.	—	0.5	5	4.95			4.95	5	—	V	
	—	0.10	10	9.95			9.95	10	—		
	—	0.15	15	14.95			14.95	—	—		
Input Current, I _{IN} Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^\circ\text{C}$; Input $t_r, t_f = 20\text{ ns}$, $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS		LIMITS		UNITS
	V_{DD}		TYP.	MAX.	
Propagation Delay Time: t_{PHL} t_{PLH}	5		190	380	ns
	10		90	180	
	15		65	130	
Transition Time, t_{THL} t_{TLH}	5		100	200	ns
	10		50	100	
	15		40	80	
Input Capacitance, C_{IN}	Any Input		5	7.5	pF

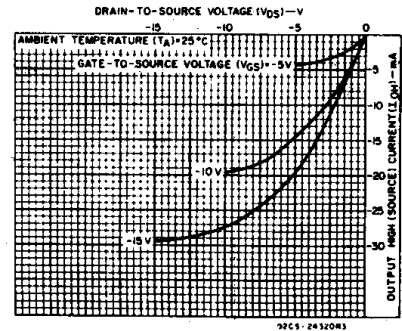


Fig. 8 — Typical output high (source) current characteristics.

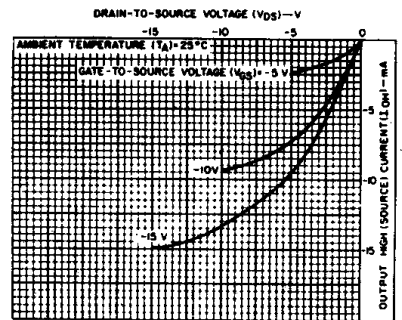


Fig. 9 — Minimum output high (source) current characteristics.

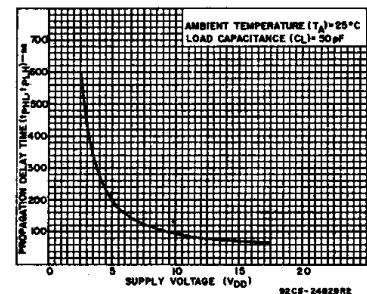


Fig. 10 — Typical propagation delay time vs. supply voltage.

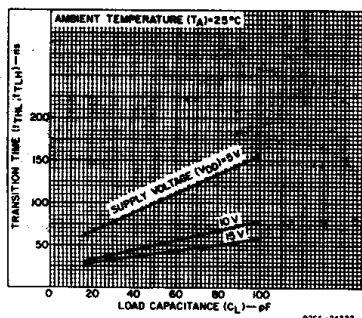


Fig. 11 — Typical transition time vs. load capacitance.

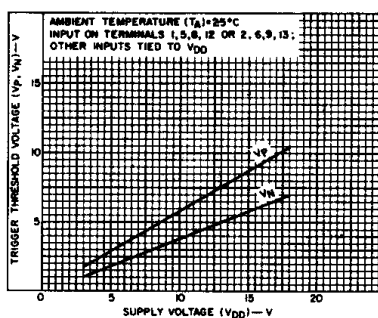


Fig. 12 — Typical trigger threshold voltage vs. V_{DD} .

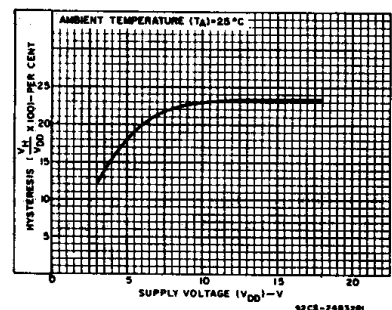


Fig. 13 — Typical per cent hysteresis vs. supply voltage.

CD4093B Types

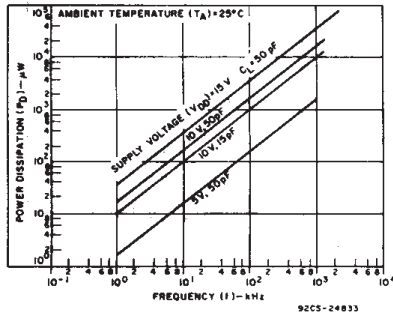


Fig. 14 - Typical power dissipation vs. frequency characteristics.

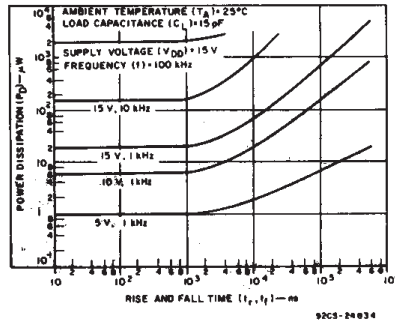


Fig. 15 - Typical power dissipation vs. rise and fall times.

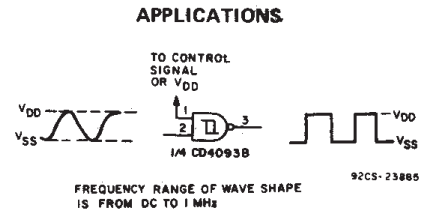


Fig. 16 - Wave shaper.

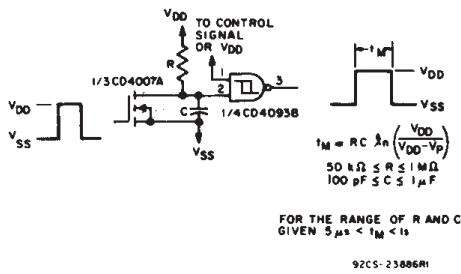


Fig. 17 - Monostable multivibrator.

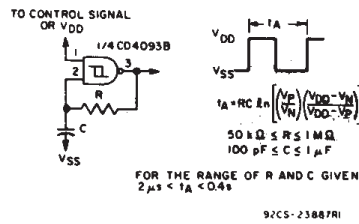


Fig. 18 - Astable multivibrator.

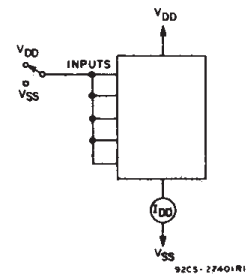


Fig. 19 - Quiescent device current test circuit.

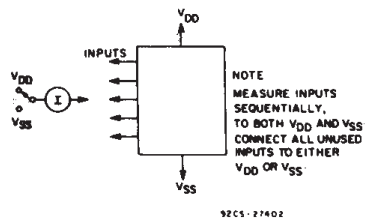


Fig. 20 - Input current test circuit.

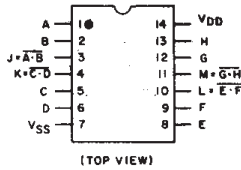


Fig. 21 - Contact Debouncer

Fig. 21 - Contact Debouncer

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
7704602CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
CD4093BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4093BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4093BF	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
CD4093BF3A	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
CD4093BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BM96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4093BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder

temperature.

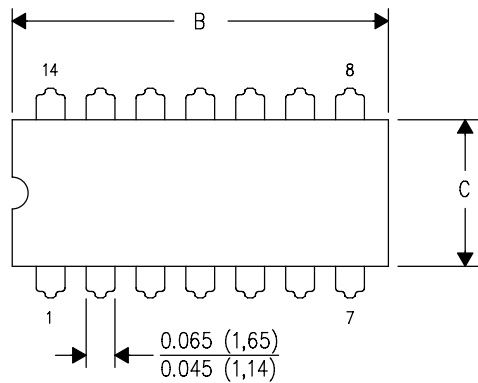
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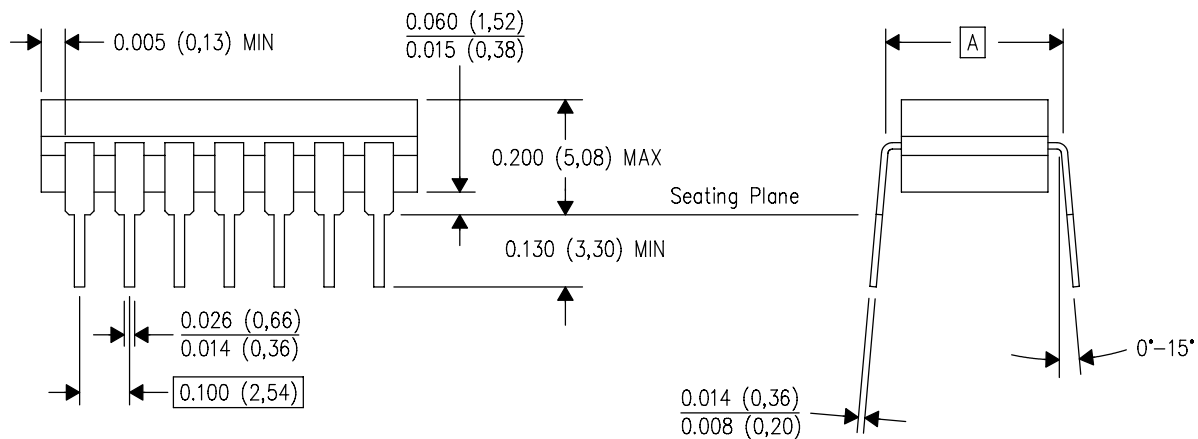
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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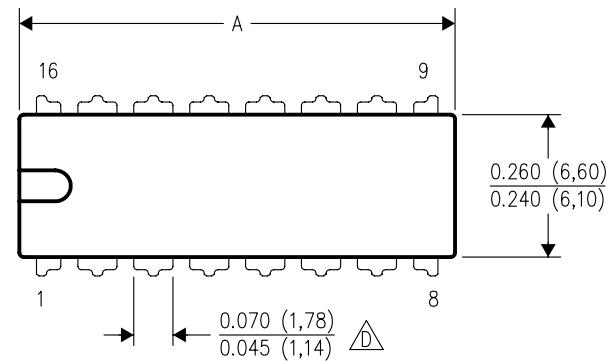
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

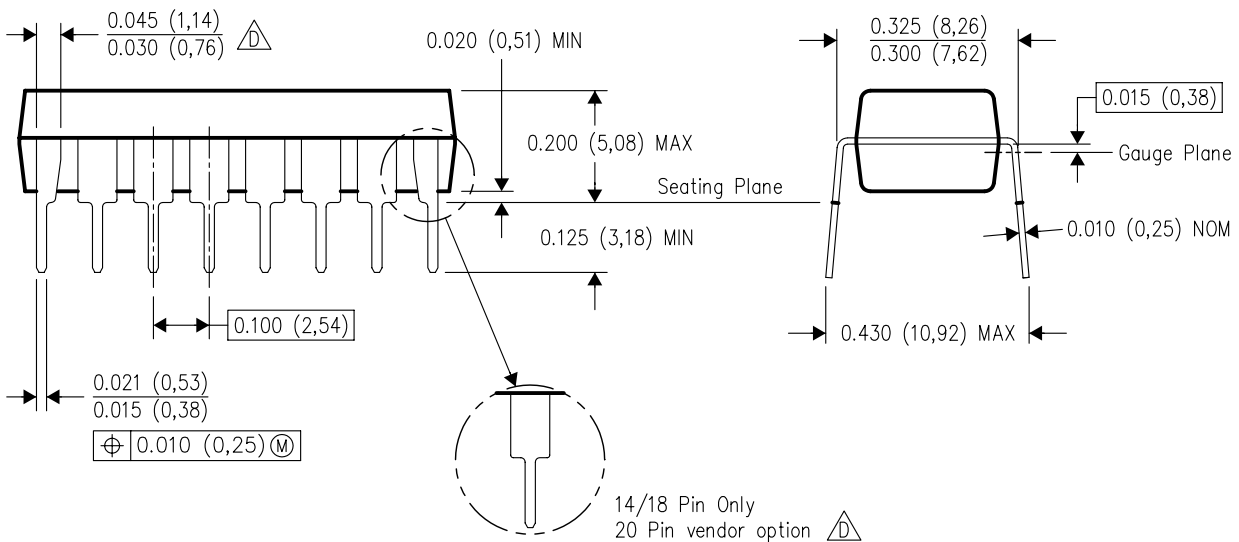
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



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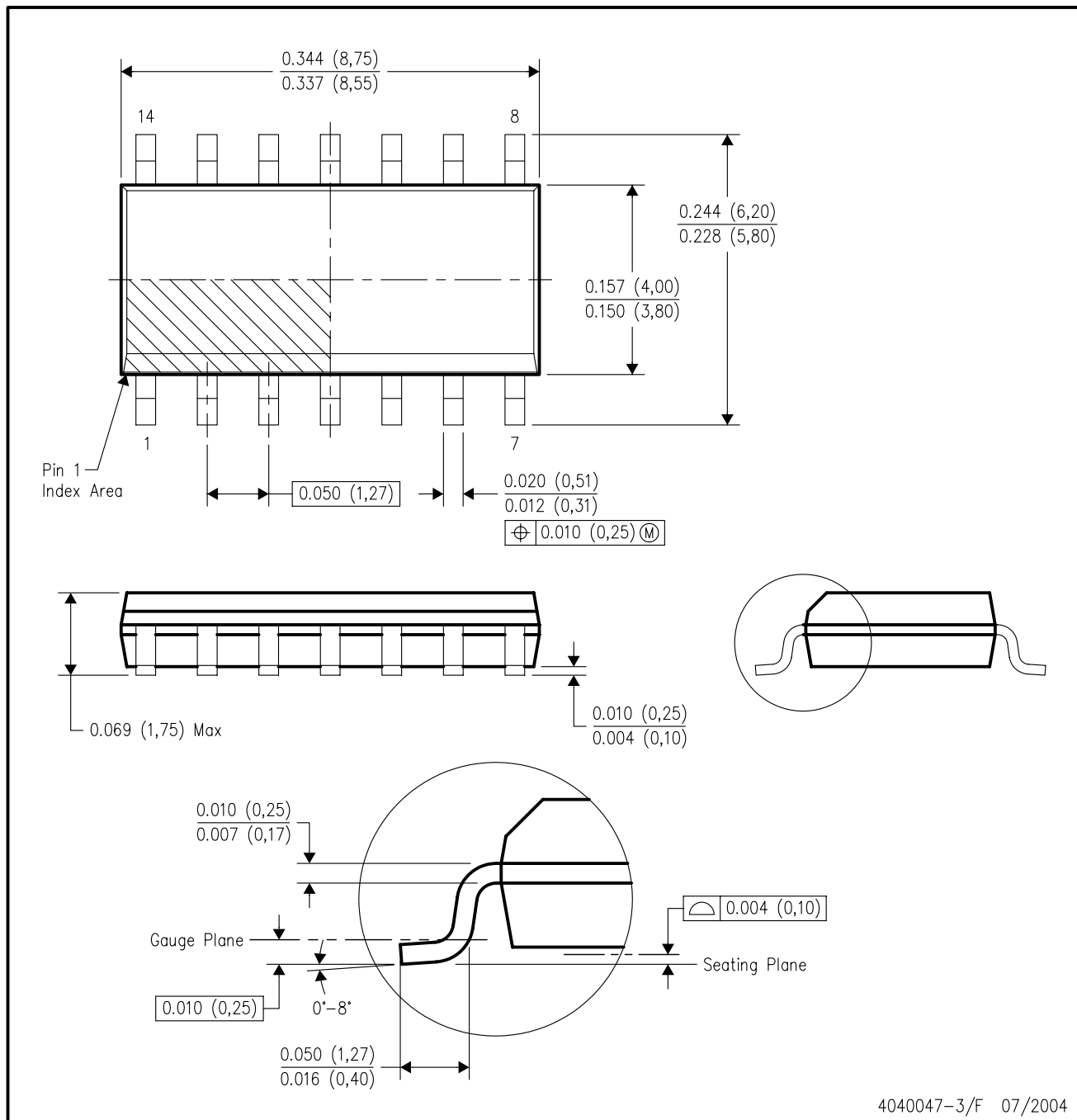
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
-  C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
-  D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



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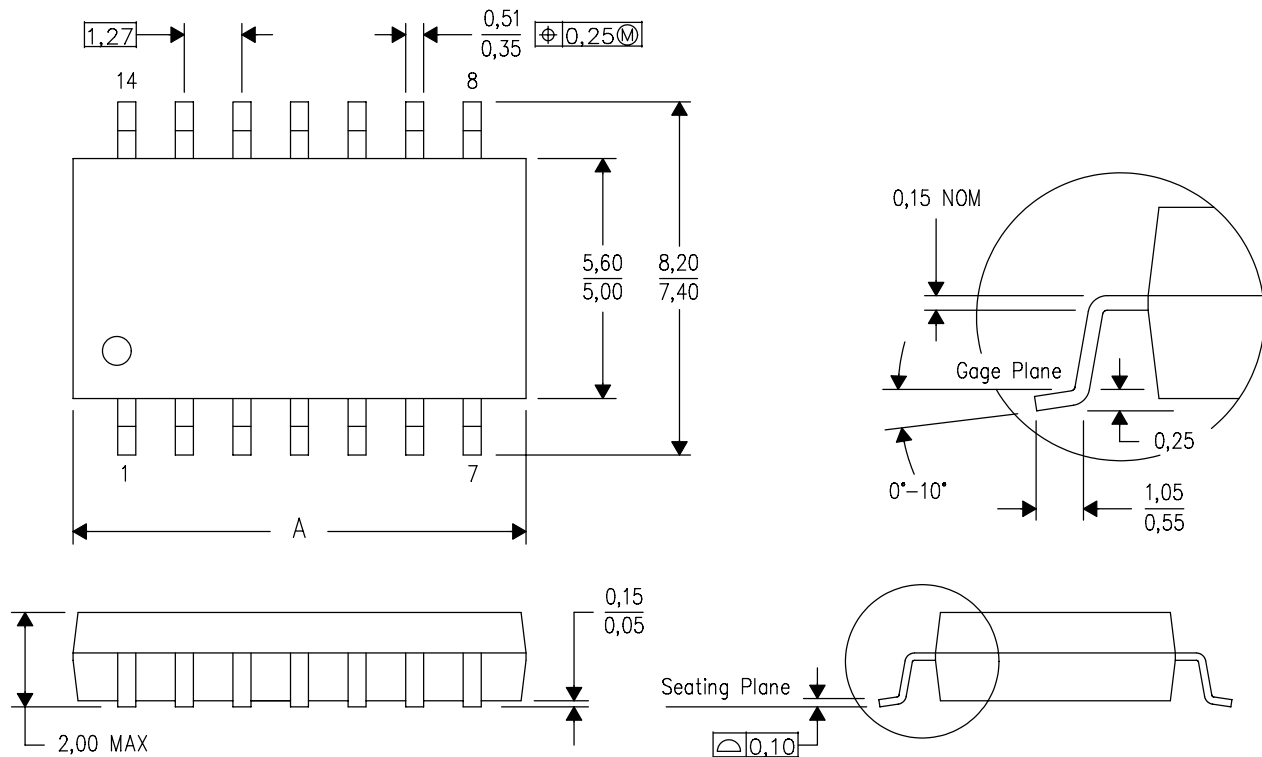
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

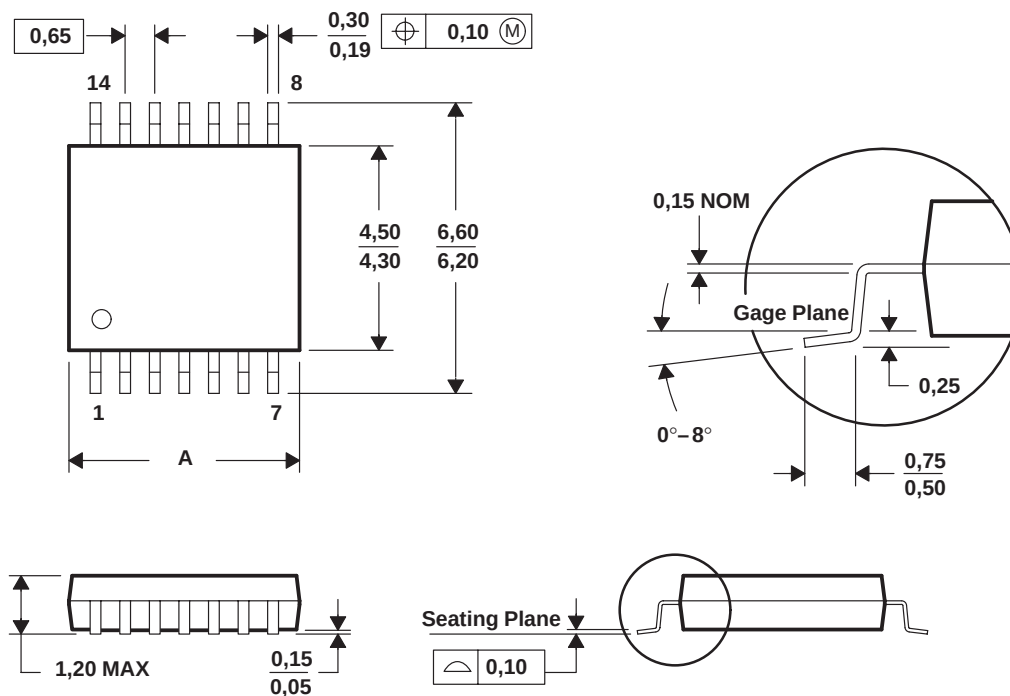
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



PINS **	8	14	16	20	24	28
DIM						
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

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 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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